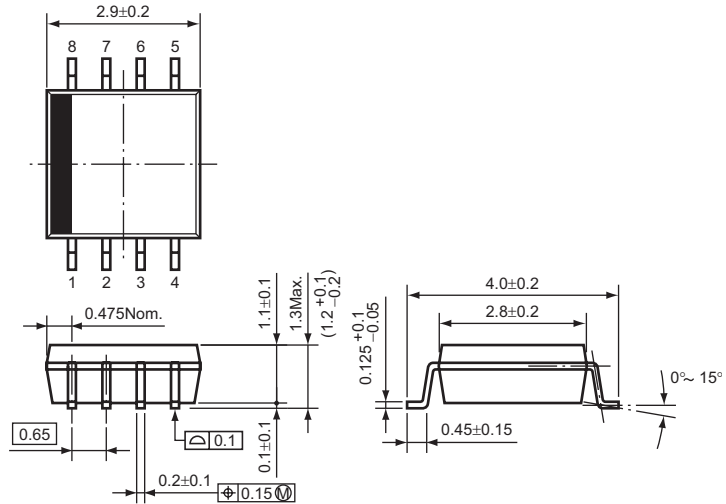


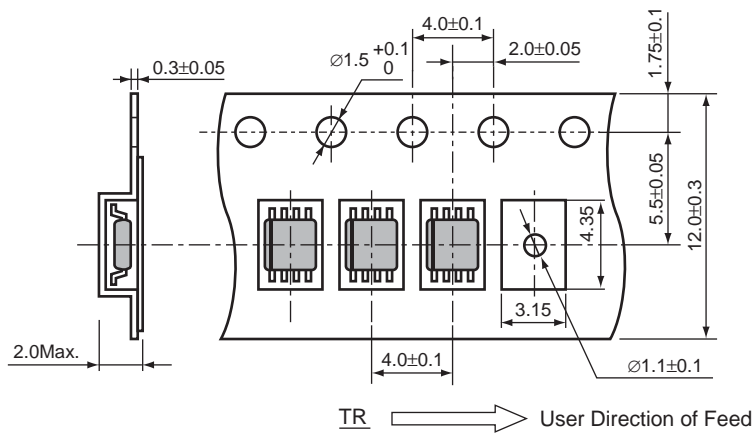
• SSOP-8G

Unit: mm

PACKAGE DIMENSIONS

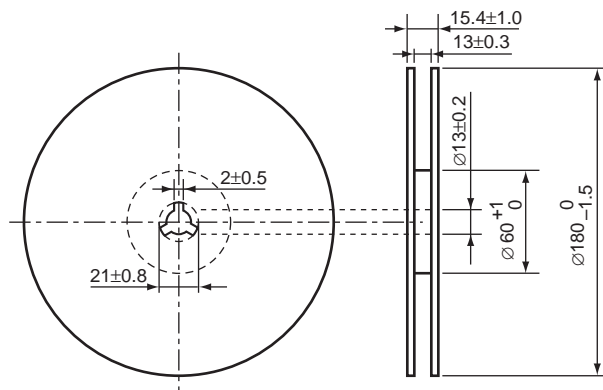


TAPING SPECIFICATION



TAPING REEL DIMENSIONS REUSE REEL (EIAJ-RRM-12Bc)

(1reel=3,000pcs)



## POWER DISSIPATION (SSOP-8G)

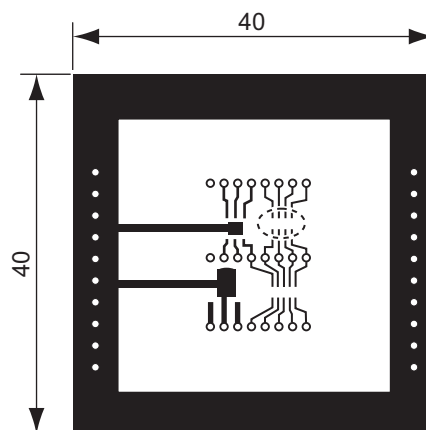
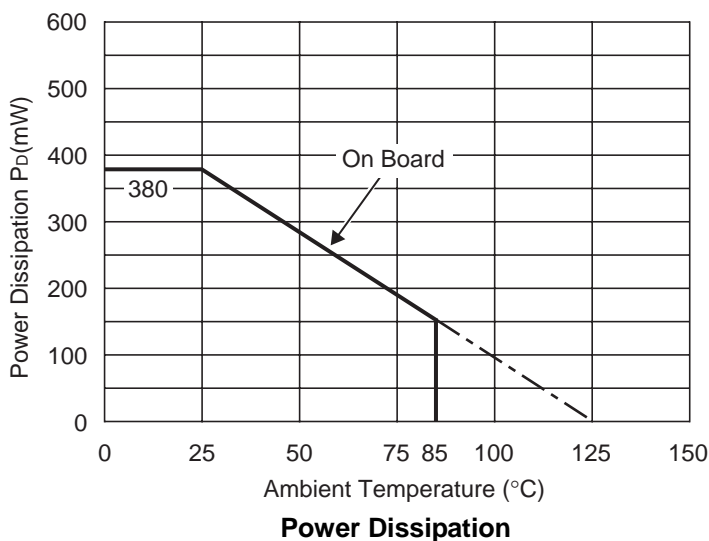
This specification is at mounted on board. Power Dissipation ( $P_D$ ) depends on conditions of mounting on board. This specification is based on the measurement at the condition below:

### Measurement Conditions

	Standard Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plastic (Double sided)
Board Dimensions	40mm × 40mm × 1.6mm
Copper Ratio	Top side : Approx. 50% , Back side : Approx. 50%
Through-hole	φ0.5mm × 44pcs

### Measurement Result (T<sub>opt</sub>=25°C, T<sub>jmax</sub>=125°C)

	Standard Land Pattern
Power Dissipation	380mW
Thermal Resistance	$\theta_{ja}=(125-25^{\circ}\text{C})/0.38\text{W}=263^{\circ}\text{C/W}$
Thermal Resistance	$\theta_{jc}=60^{\circ}\text{C/W}$



**Measurement Board Pattern**  
○ IC Mount Area (Unit: mm)

## RECOMMENDED LAND PATTERN

